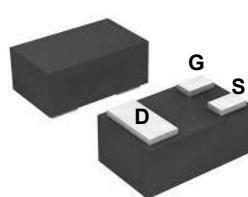
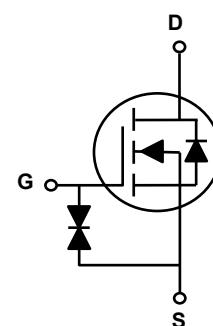


Main Product Characteristics

BV _{DSS}	20V
R _{DS(ON)}	280mΩ
I _D	1.4A



SOT-883



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSF0202A utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings (T_J=25°C unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	±12	V
Drain Current-Continuous (T _A =25°C) ^{1,3}	I _D	0.7	A
Drain Current-Continuous (T _A =70°C) ^{1,3}		0.9	
Drain Current-Pulsed ²	I _{DM}	1.9	A
Diode Continuous Forward Current	I _S	0.6	A
Power Dissipation (T _A =25°C)	P _D	0.7	W
Power Dissipation (T _A =70°C)		0.4	W
Thermal Resistance, Junction-to-Ambient ²	R _{θJA}	180	°C/W
Maximum Junction Temperature	T _J	150	°C
Operating/Storage Temperature Range	T _J / T _{STG}	-55 To +150	°C

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On/Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	20	-	-	V
Drain-Source Leakage Current	I_{DSS}	$\text{V}_{\text{DS}}=16\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Source Leakage Current	I_{GSS}	$\text{V}_{\text{GS}}=\pm 8\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	± 10	μA
Static Drain-Source On-Resistance	$\text{R}_{\text{DS}(\text{ON})}$	$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=0.55\text{A}$	-	280	450	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=2.5\text{V}, \text{I}_D=0.45\text{A}$	-	450	600	
		$\text{V}_{\text{GS}}=1.8\text{V}, \text{I}_D=0.35\text{A}$	-	650	800	
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}, \text{I}_{\text{DS}}=250\mu\text{A}$	0.5	-	1.0	V
Forward Transconductance	g_{fs}	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=0.55\text{A}$	-	1.7	-	S
Dynamic and Switching Characteristics						
Total Gate Charge	Q_g	$\text{V}_{\text{GS}}=2.5\text{V}, \text{V}_{\text{DS}}=10\text{V}, \text{I}_D=1\text{A}$	-	1.1	-	nC
Total Gate Charge	Q_g	$\text{V}_{\text{DS}}=10\text{V}, \text{I}_D=1\text{A}, \text{V}_{\text{GS}}=4.5\text{V}$	-	2	-	nC
Gate-Source Charge	Q_{gs}		-	0.3	-	
Gate-Drain Charge	Q_{gd}		-	0.3	-	
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$\text{V}_{\text{DS}}=10\text{V}, \text{R}_{\text{GEN}}=6\Omega, \text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=2\text{A}$	-	1.2	-	nS
Rise Time	t_r		-	25	-	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	14	-	
Fall Time	t_f		-	15	-	
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=10\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{F}=1\text{MHz}$	-	43	-	pF
Output Capacitance	C_{oss}		-	9	-	
Reverse Transfer Capacitance	C_{rss}		-	6	-	
Drain-Source Diode Characteristics and Maximum Ratings						
Diode Forward Voltage	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_{\text{SD}}=0.35\text{A}$	-	-	1.1	V
Reverse Recovery Time	t_{rr}	$\text{I}_{\text{F}}=1\text{A}, \text{di}/\text{dt}=100\text{A}/\mu\text{s}$	-	9	-	nS
Reverse Recovery Charge	Q_{rr}		-	1	-	nC

Note:

- The value of $\text{R}_{\text{DS(A)}}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design.
- Repetitive rating, pulse width limited by junction temperature .
- The current rating is based on the $t<10\text{s}$ junction to ambient thermal resistance rating.

Typical Electrical and Thermal Characteristic Curves

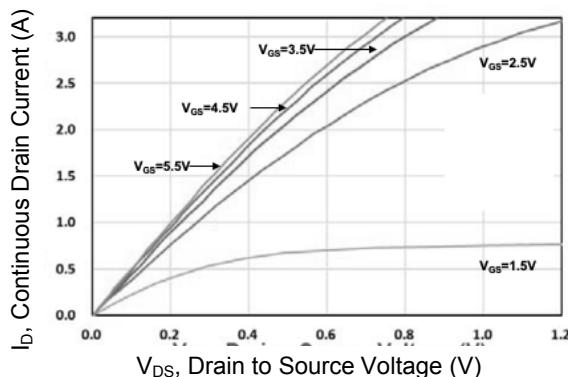


Figure 1. Typical Output Characteristics

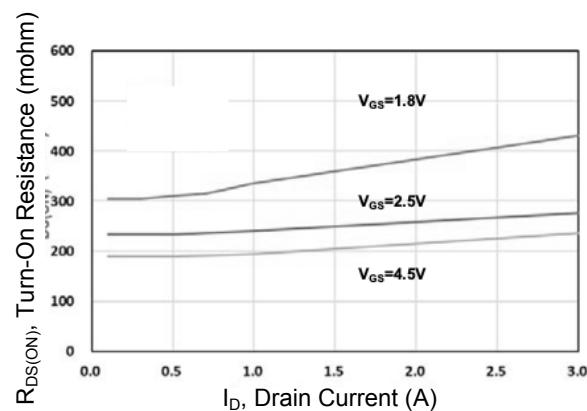


Figure 2. Turn-On Resistance vs. I_D

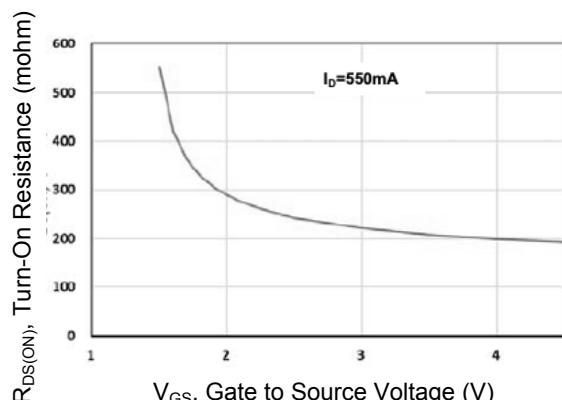


Figure 3. Turn-On Resistance vs. V_{GS}

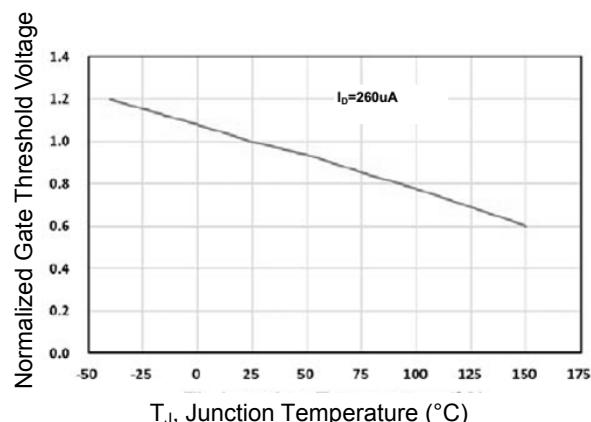


Figure 4. Normalized V_{th} vs. T_J

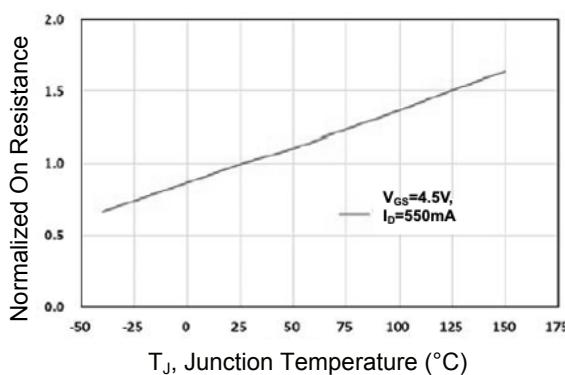


Figure 5. Normalized $R_{DS(ON)}$ vs. T_J

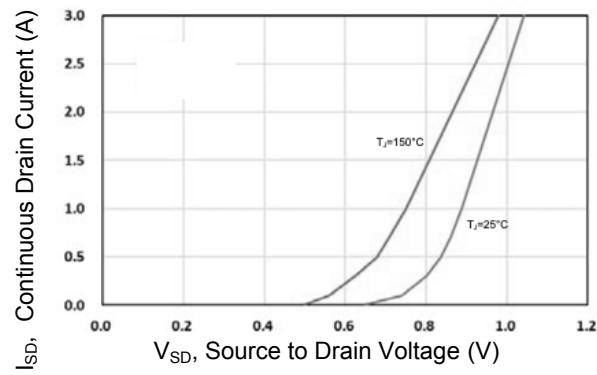


Figure 6. Source-Drain Diode Forward

Typical Electrical and Thermal Characteristic Curves

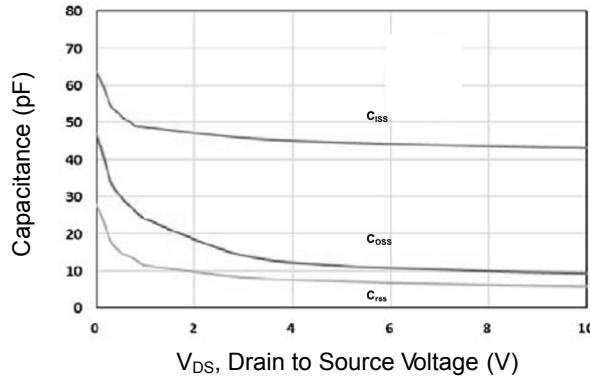


Figure 7. Capacitance Characteristics

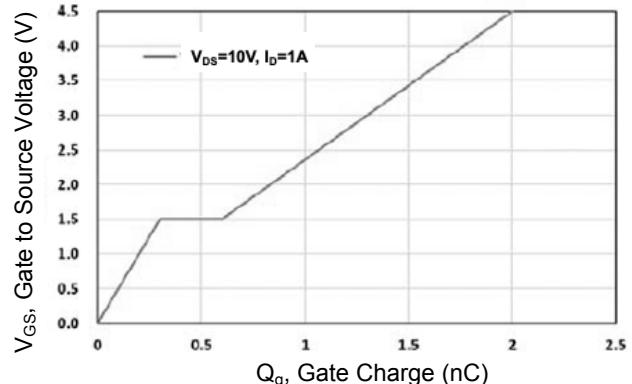


Figure 8. Gate Charge Characteristics

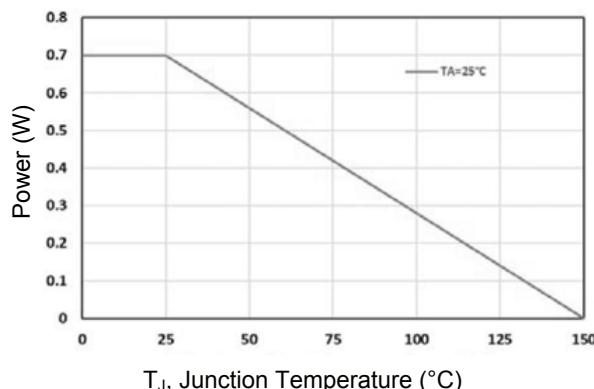


Figure 9. Power Dissipation

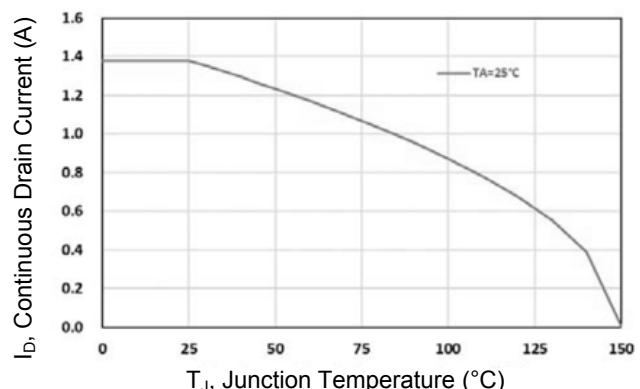


Figure 10. Continuous Drain Current vs. T_c

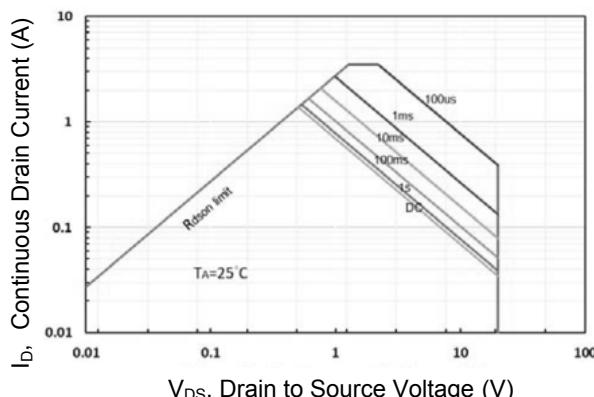


Figure 11. Maximum Safe Operation Area

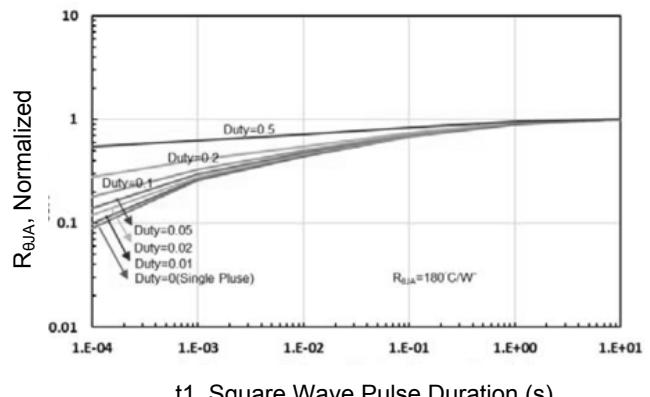
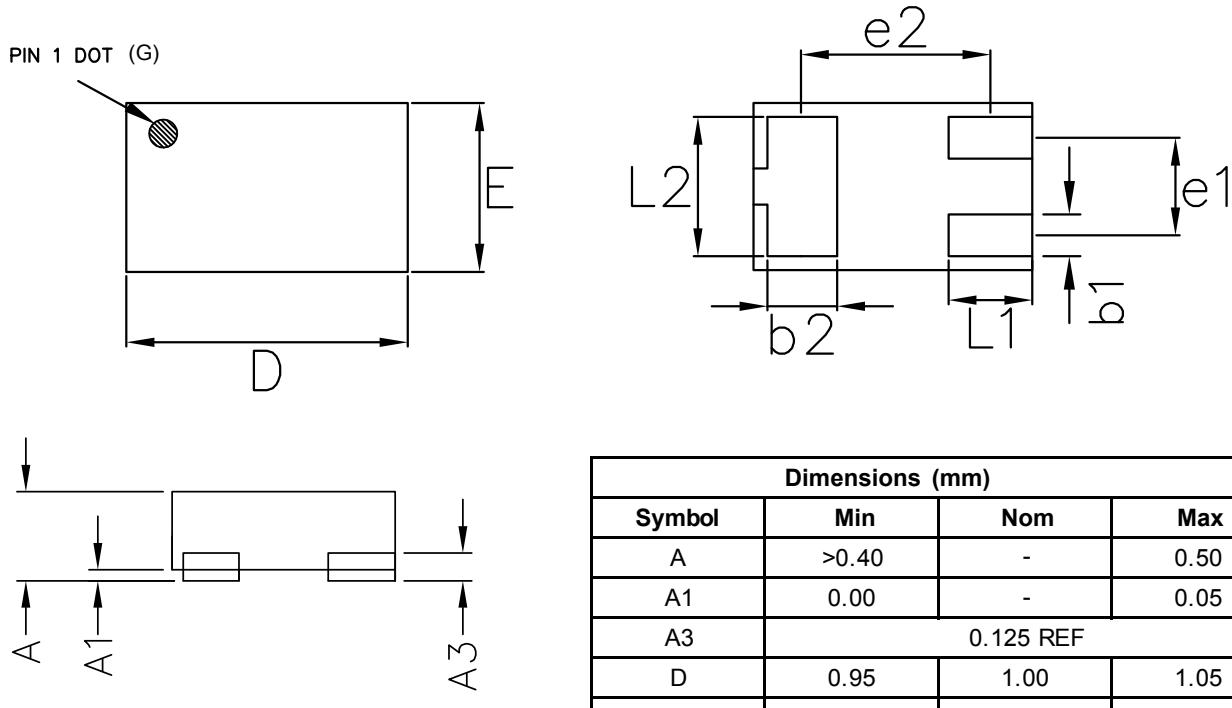


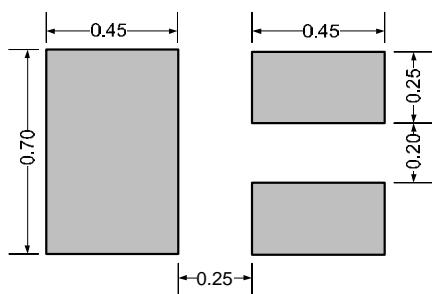
Figure 12. $R_{\theta JA}$ Transient Thermal Impedance

Package Outline Dimensions (SOT-883)



Dimensions (mm)			
Symbol	Min	Nom	Max
A	>0.40	-	0.50
A1	0.00	-	0.05
A3	0.125 REF		
D	0.95	1.00	1.05
E	0.55	0.60	0.65
b1	0.10	0.15	0.20
b2	0.20	0.25	0.30
L1	0.20	0.30	0.40
L2	0.40	0.50	0.60
e1	0.35 BSC		
e2	0.675 BSC		

Recommend Pad Layout



Order Information

MPN	Package	Marking	Carrier	Quantity	HSF Status
GSFW0202A	SOT-883	4B	Tape & Reel	10,000pcs	RoHS Compliant